Nch 600V 24A Power MOSFET

V _{DSS}	600V
R _{DS(on)} (Max.)	0.165Ω
I _D	±24A
P_D	74W

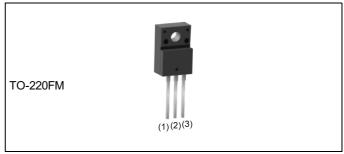
Features

- 1) Low on-resistance
- 2) Ultra fast switching
- 3) Parallel use is easy
- 4) Pb-free plating; RoHS compliant

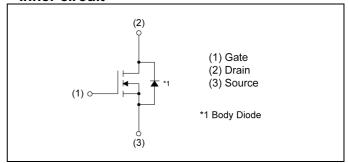
Application

Switching

Outline



●Inner circuit



Packaging specifications

Code	Packing
C7 G	Tube
C7	Tube*
- (Blank)	Bulk*

^{*}Package dimensions are different

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage	V_{DSS}	600	V	
Continuous drain current		I _D *1	±24	Α
Pulsed drain current	I _{DP} *2	±72	Α	
static		V	±20	V
Gate - Source voltage	AC(f>1Hz)	V_{GSS}	±30	V
Avalanche current, single pulse		I _{AS}	4.1	Α
Avalanche energy, single pulse		E _{AS} *3	497	mJ
Power dissipation (T _c = 25°C)	P _D	74	W	
Junction temperature	T _j	150	°C	
Operating junction and storage tempe	rature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Downwortow	Cymah al	Values			1.1
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC} *4	-	-	1.7	°C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	70	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

• Electrical characteristics $(T_a = 25^{\circ}C)$

Parameter	Cumb al	Conditions	Values			Unit
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = 1mA$	600	-	-	V
		V _{DS} = 600V, V _{GS} = 0V				
Zero gate voltage drain current	I _{DSS}	$T_j = 25^{\circ}C$	-	-	100	μΑ
		$T_j = 125^{\circ}C$	-	-	1000	
Gate - Source leakage current	I _{GSS}	V_{GS} = ±20V, V_{DS} = 0V	1	-	±100	nA
Gate threshold voltage	$V_{GS(th)}$	V_{DS} = 10V, I_D = 1mA	3	-	5	٧
		V _{GS} = 10V, I _D = 11.3A				
Static drain - source on - state resistance	R _{DS(on)} *5	$T_j = 25^{\circ}C$	-	0.150	0.165	Ω
		$T_j = 125^{\circ}C$	-	0.320	-	
Gate resistance	R_{G}	f = 1MHz, open drain	-	1.9	-	Ω

● Electrical characteristics (T_a = 25°C)

Darramatar	Cymah al	Conditions	Values			Linit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Transfer Admittance	Y _{fs} *5	V _{DS} = 10V, I _D = 12A	6.5	13.0	-	S
Input capacitance	C _{iss}	V _{GS} = 0V	-	2000	-	,
Output capacitance	C _{oss}	V _{DS} = 25V	-	1500	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	60	1	
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq 300V$, $V_{GS} = 10V$	-	30	-	
Rise time	t _r *5	I _D = 12A	-	50	-	20
Turn - off delay time	t _{d(off)} *5	$R_L \simeq 27.4\Omega$	-	60	-	ns
Fall time	t _f *5	$R_G = 10\Omega$	-	12	1	

● Gate charge characteristics (T_a = 25°C)

Darameter	Complete all	Conditions	Values			l limit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Q_g^{*5}	V _{DD} ≈ 300V	-	45	-	
Gate - Source charge	Q _{gs} *5	I _D = 24A	-	13	-	nC
Gate - Drain charge	Q _{gd} *5	V _{GS} = 10V	-	20	-	
Gate plateau voltage	V _(plateau)	V _{DD} ≈ 300V, I _D = 24A	-	6.8	-	V

^{*1} Limited only by maximum channel temperature allowed.

^{*2} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*3} L \doteqdot 70mH, V_{DD}=50V, R_G=25 Ω , STARTING T $_{j}$ =25 $^{\circ}$ C

^{*4} T_C=25°C

^{*5} Pulsed

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Cumah al	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	I _S *1	T - 25°C	-	-	24	А
Pulse forward current	I _{SP} *2	T _C = 25°C	-	-	72	А
Forward voltage	V _{SD} *5	V _{GS} = 0V, I _S = 24A	-	-	1.5	V
Reverse recovery time	t _{rr} *5		-	510	-	ns
Reverse recovery charge	Q _{rr} *5	I _S = 24A di/dt = 100A/µs	-	9.0	-	μC
Peak reverse recovery current	I _{rrm} *5	- α, ατ 100/ γμο	-	32.5	-	Α

Typical transient thermal characteristics

Symbol	Value	Unit
R _{th1}	0.122	
R _{th2}	0.671	K/W
R _{th3}	2.15	

Symbol	Value	Unit
C _{th1}	0.00308	
C _{th2}	0.0414	Ws/K
C _{th3}	0.504	

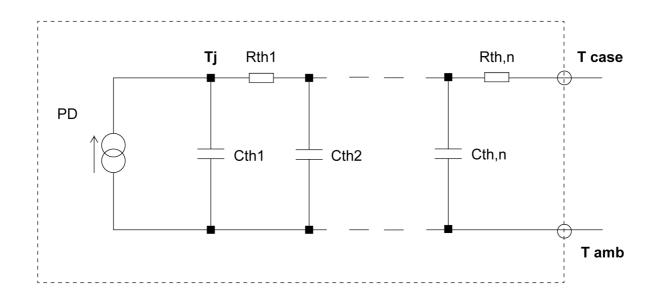


Fig.1 Power Dissipation Derating Curve

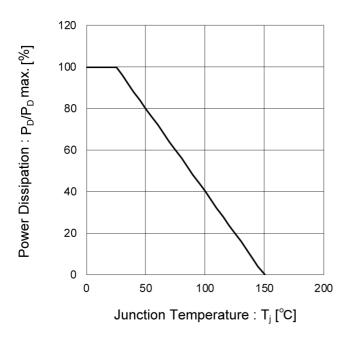


Fig.2 Drain Current Derating Curve

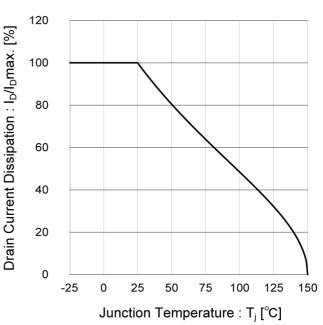


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

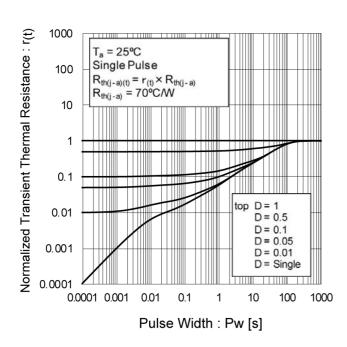
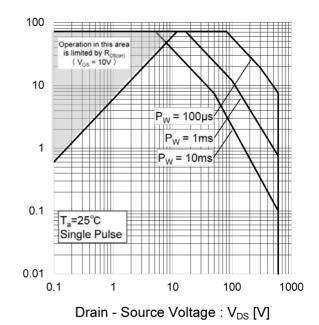


Fig.4 Maximum Safe Operating Area



Drain Current : I_D [A]

Fig.5 Avalanche Energy Derating Curve

120 Avalanche Energy: EAS / EAS max [%] 100 80 40 20 0 0 25 50 75 100 125 150 175 Junction Temperature : T_j [°C]

Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

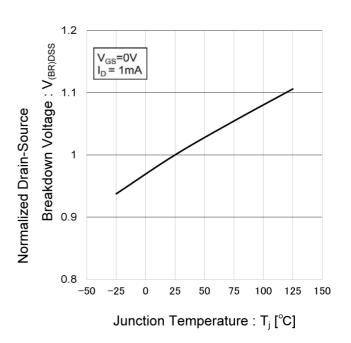


Fig.7 Typical Output Characteristics(I)

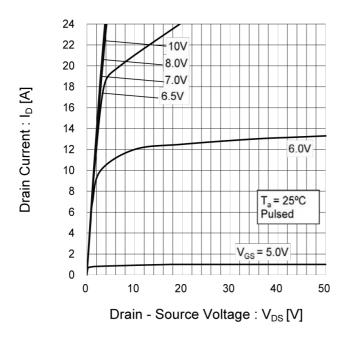
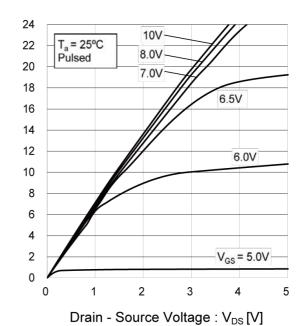


Fig.8 Typical Output Characteristics(II)



Drain Current : I_D [A]

Fig.9 Typical Transfer Characteristics

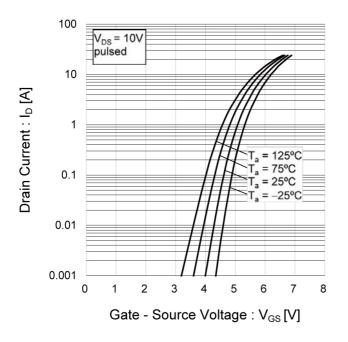


Fig.10Gate Threshold

Voltage vs. Junction Temperature

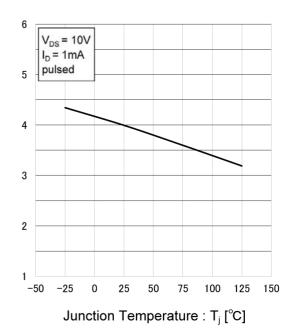


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

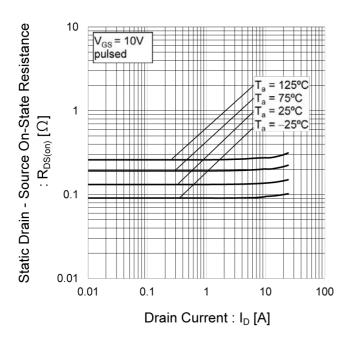
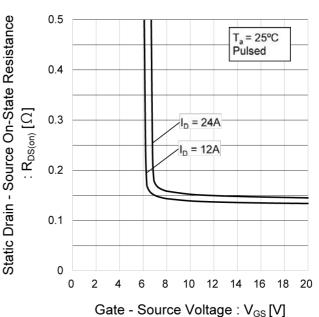


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



Gate Threshold Voltage: V_{GS(th)} [V]

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

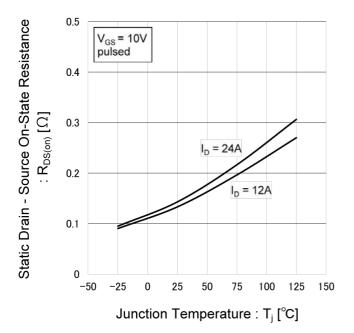
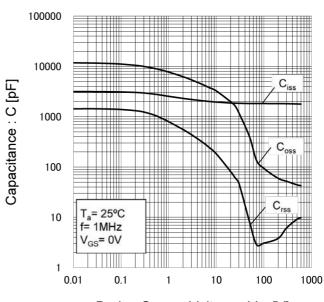


Fig.14 Typical Capacitance vs.

Drain - Source Voltage



Drain - Source Voltage: V_{DS}[V]

Fig.15 Switching Characteristics

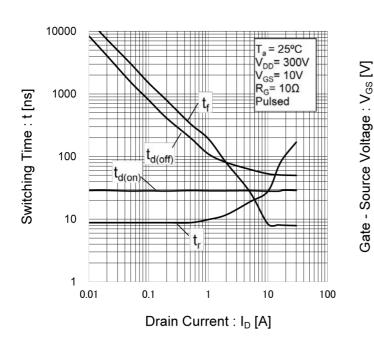


Fig.16 Typical Gate Charge

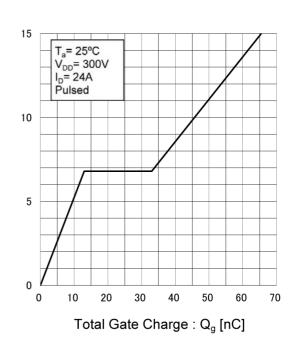


Fig.17 Source Current vs. Source - Drain Voltage

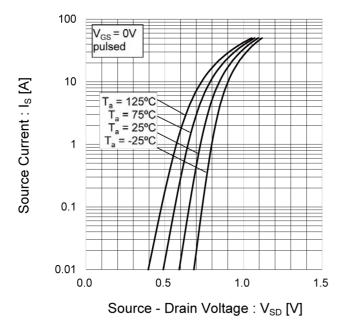
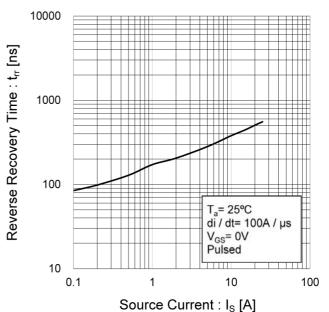


Fig.18 Reverse Recovery Time vs. Source Current



Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

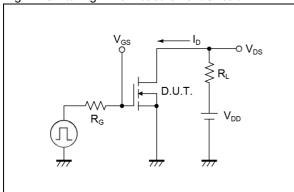


Fig.2-1 Gate Charge Measurement Circuit

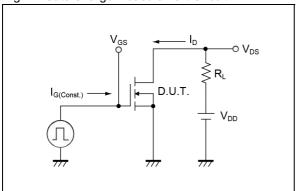


Fig.3-1 Avalanche Measurement Circuit

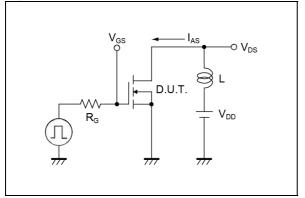


Fig.4-1 trr Measurement Circuit

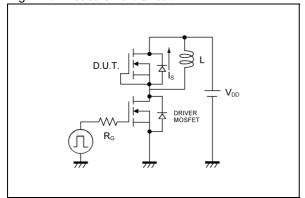


Fig.1-2 Switching Waveforms

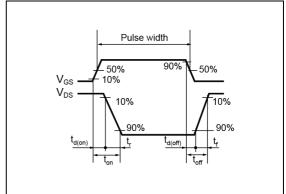


Fig.2-2 Gate Charge Waveform

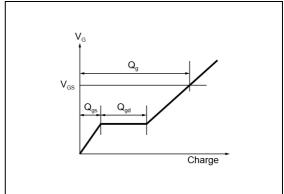


Fig.3-2 Avalanche Waveform

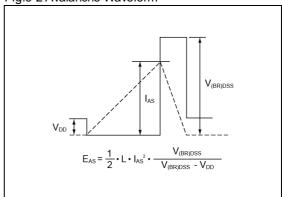
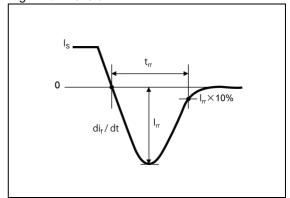
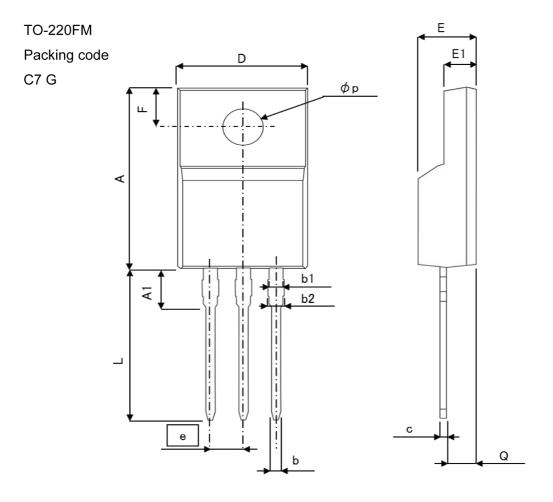


Fig.4-2 trr Waveform



Dimensions

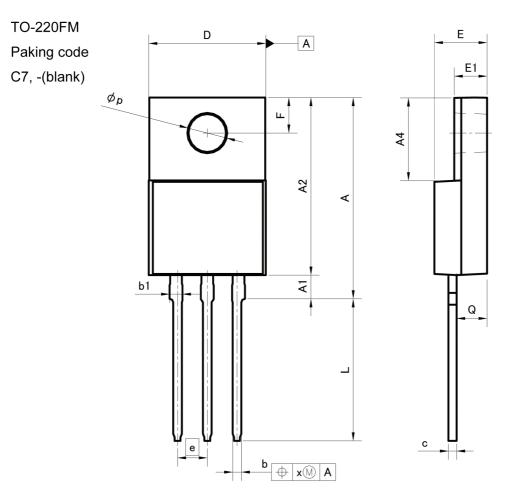


DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	15.67	16.27	0.617	0.641
A1	3.03	3.43	0.119	0.135
b	0.70	0.95	0.028	0.037
b1	1.00	1.40	0.039	0.055
b2	1.10	1.50	0.043	0.059
С	0.45	0.65	0.018	0.026
D	9.90	10.30	0.390	0.406
E	4.60	5.00	0.181	0.197
E1	2.44	2.74	0.096	0.108
е	2.	54	0.1	00
F	3.10	3.50	0.122	0.138
L	12.6	13.6	0.946	0.535
р	2.98	3.38	0.117	0.133
Q	2.25	3.25	0.089	0.128

Dimension in mm/inches



Dimensions



DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	16.60	17.60	0.654	0.693
A1	1.80	2.20	0.071	0.087
A2	14.80	15.40	0.583	0.606
A4	6.80	7.20	0.268	0.283
b	0.70	0.90	0.028	0.035
b1	1.10	1.50	0.043	0.059
С	0.70	0.85	0.028	0.033
D	9.90	10.30	0.390	0.406
E	4.40	4.80	0.173	0.189
е	2.	54	0.1	00
E1	2.70	3.00	0.106	0.118
F	2.80	3.20	0.110	0.126
L	11.50	12.50	0.453	0.492
р	3.00	3.40	0.118	0.134
Q	2.10	3.10	0.083	0.122
х	_	0.38	a—3	0.015

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
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CLASSIV		CLASSⅢ	

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 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
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- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
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- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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